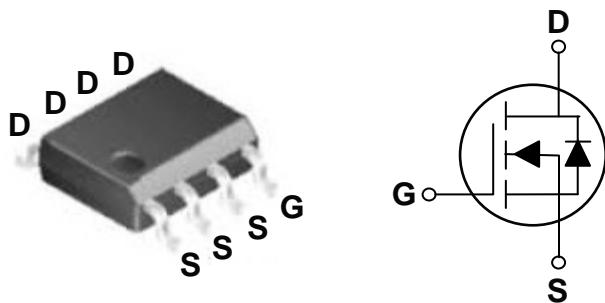


40V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOP8 Pin Configuration



BVDSS	RDS(ON)	ID
40V	9mΩ	15A

Features

- 40V, 15A, RDS(ON)=9mΩ @VGS = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications
- Hand-Held Device

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	15	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	9.5	A
I_{DM}	Drain Current – Pulsed ¹	60	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	5.4	W
	Power Dissipation – Derate above 25°C	0.043	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	23	°C/W



FTK4906

40V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=40\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=32\text{V}$, $V_{GS}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=8\text{A}$	---	7	9	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=4\text{A}$	---	9.5	13	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-5	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_D=10\text{A}$	---	13	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=20\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=8\text{A}$	---	12.2	24	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	3.3	7	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	6.7	13	
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$	---	13.2	25	ns
T_r	Rise Time ^{2,3}		---	2.2	5	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	72	130	
T_f	Fall Time ^{2,3}		---	4.5	10	
C_{iss}	Input Capacitance		---	1220	2200	pF
C_{oss}	Output Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	130	250	
C_{rss}	Reverse Transfer Capacitance		---	55	110	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	2.2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	15	A
			---	---	30	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
			---	17	---	ns
Q_{rr}	Reverse Recovery Charge ³	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	---	2.8	---	nC

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

40V N-Channel MOSFETs

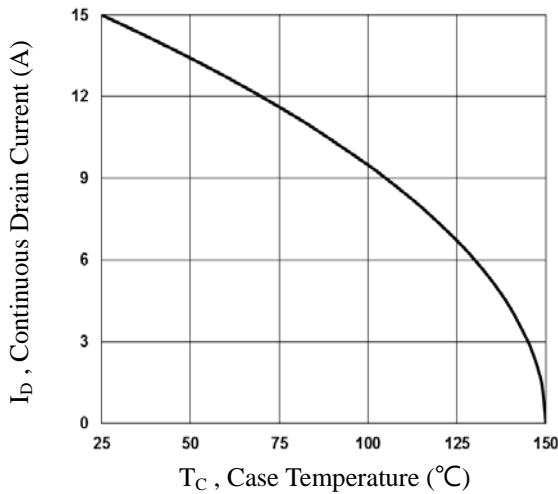


Fig.1 Continuous Drain Current vs. T_C

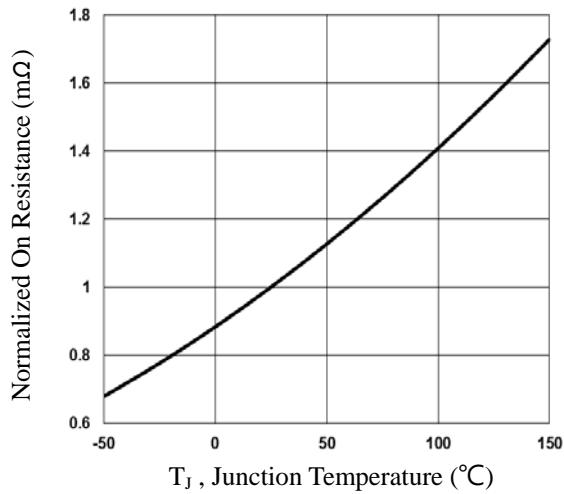


Fig.2 Normalized RDSON vs. T_J

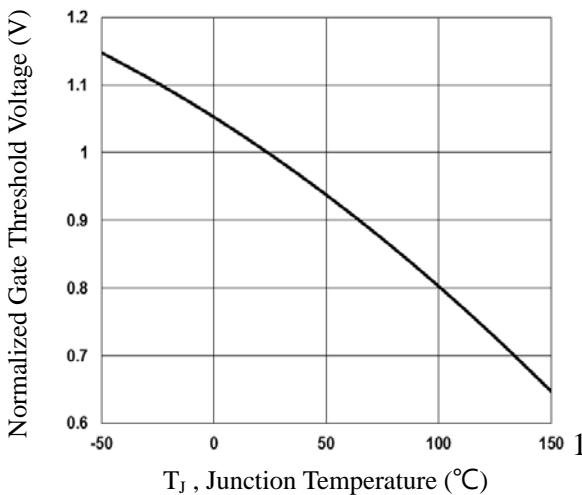


Fig.3 Normalized V_{th} vs. T_J

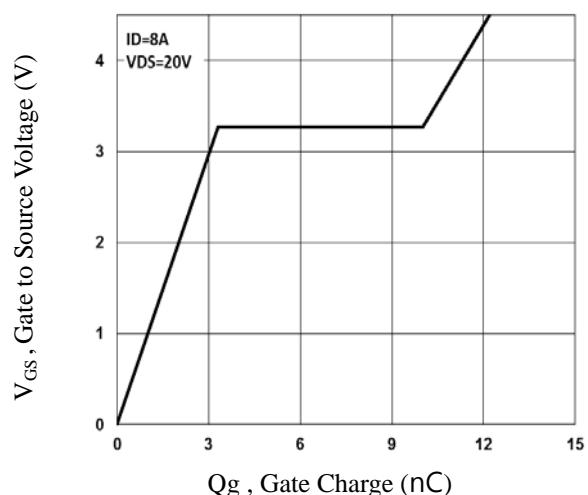


Fig.4 Gate Charge Waveform

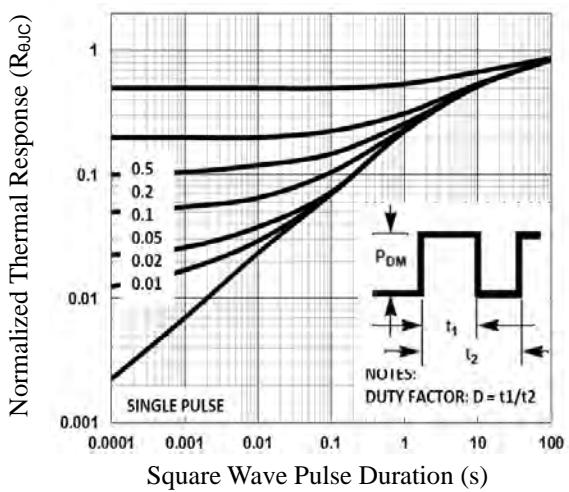


Fig.5 Normalized Transient Impedance

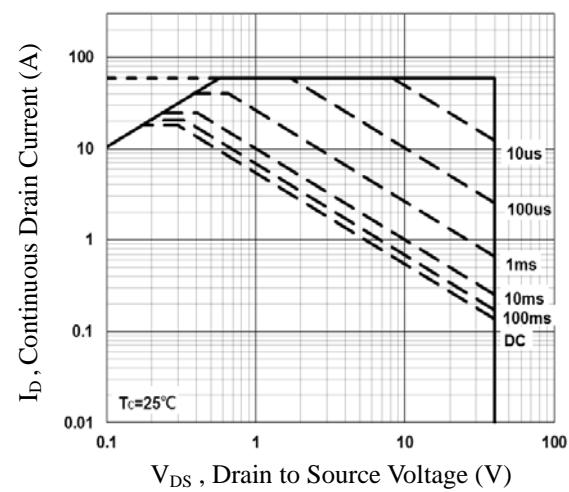


Fig.6 Maximum Safe Operation Area

40V N-Channel MOSFETs

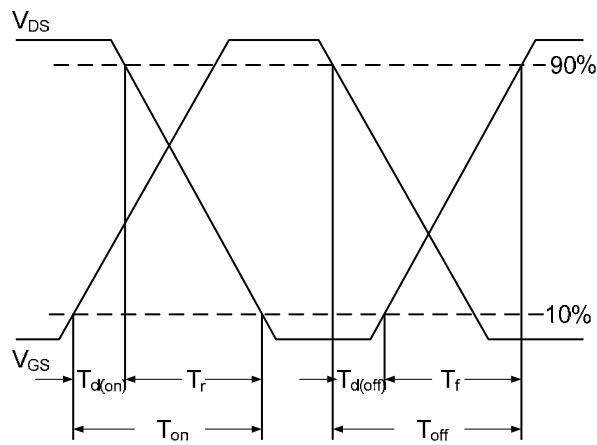


Fig.7 Switching Time Waveform

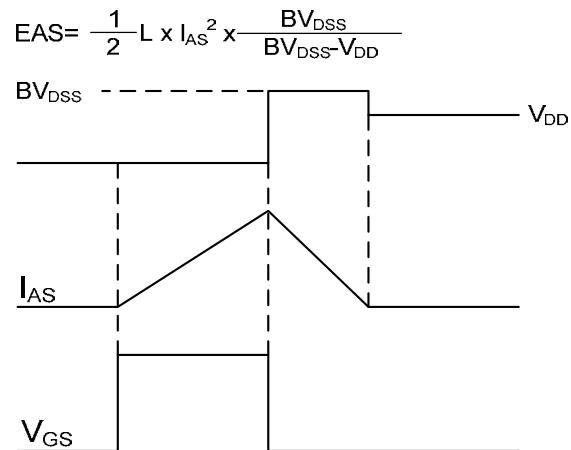
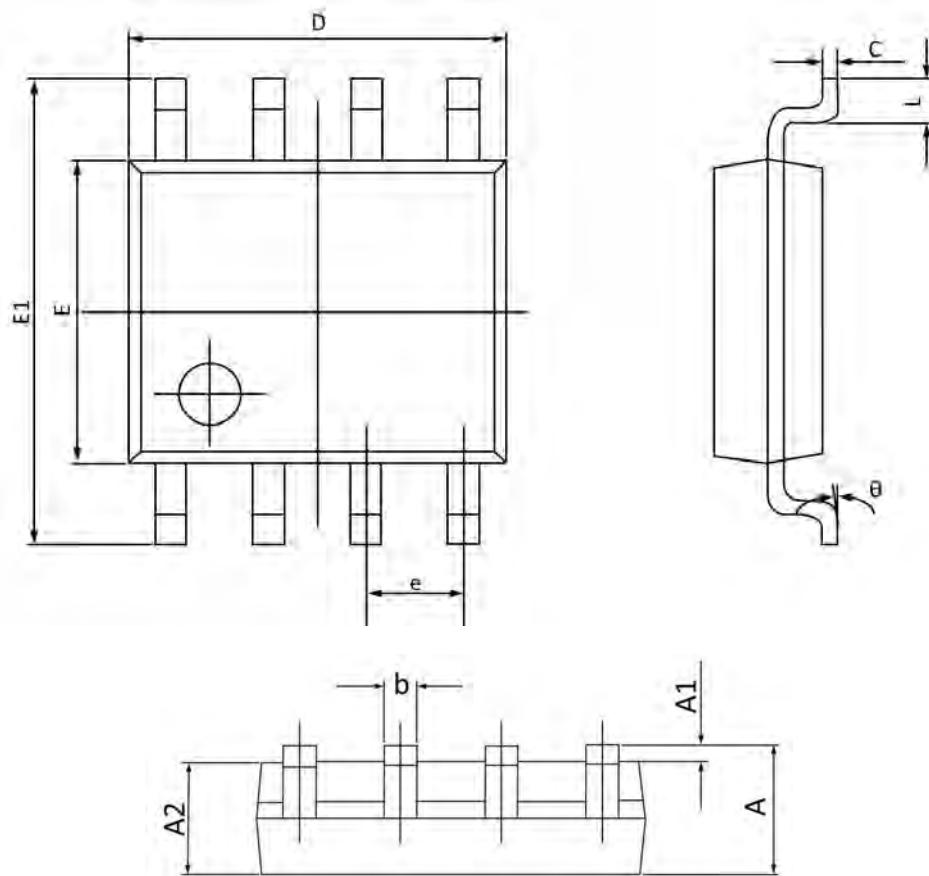


Fig.8 EAS Waveform

40V N-Channel MOSFETs

SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°